

POLISHING PAD

ABSTRACT

A polishing pad is useful planarizing semiconductor substrates. The polishing pad comprises a polymeric material having a porosity of at least 0.1 volume percent, a KEL energy loss factor at 40°C and 1 rad/sec of 385 to 750 1/Pa and a modulus E' at 40°C and 1 rad/sec of 100 to 400 MPa.

(No figure to accompany the abstract)